Silicone Adhesion Promoter

SK-AP032

Product Features:

- Significantly enhances adhesion of addition-cure silicone to stainless steel, aluminum, glass, PC, and other substrates.
- Hydrogen-containing reactive type.

Technical Specifications:

Test Item	Typical Data	Test standard
Appearance	Colorless transparent liquid	Visual inspection
Kinematic viscosity (mm^2/s @25°C)	10~100	GB/T 10247-2008
Refractive Index (25°C)	1.420~1.440	GB/T 6488
Hydrogen content (wt%)	0.20~0.35	HG/T 4804-2015

Typical Applications:

- Electronic potting compounds: Selective adhesion for addition-cure thermally conductive/flame-retardant potting gels.
- Sealants: Used in CIPG/FIPG one-component addition-cure bonding sealants.
- LED encapsulation silicones: Improves adhesion to silver-plated layers and PPA substrates.

Usage Guidelines:

- Add to the hydrogen-containing component at 1–2% of the total silicone weight.
- Recommended curing temperature: >100°C (curing time varies by application).

Packaging & Storage:

- Packed in 5KG pails or 20KG cartons.
- Store at 0–8°C. Short-term room-temperature storage (<1 month) is acceptable but not advised.
- Non-flammable; classified as non-hazardous for transport.
- Optimal use within 3 months of production. Retest required if expired.

Safety & Environmental Notes:

- Wear appropriate protective gear when handling. Refer to the MSDS for details.
- Dispose of packaging in compliance with local solid waste regulations.

Notes:

- The information contained in this document is based on reliable data we have obtained. The content, product performance improvements, and product specifications may change without prior notice.
- The information provided in this document is based on our laboratory and practical experience and is for reference only. Since the conditions and methods of using this product are beyond our control, it is essential to conduct application tests and evaluations before use.
- Some performance parameters of the product can be adjusted according to customer requirements. If needed, please contact our technical department engineers.